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## **ASE Hosts Annual Technology Forum on Packaging and Test**

*Event focuses on fostering Partnerships with Customers to collaborate on leading edge semiconductor developments*

**Taipei, Taiwan, September 3, 2003** - Advanced Semiconductor Engineering Group kicks off its annual customer event - ASE Tech Forum 2003, in Hsinchu, Taiwan on September 4 and 5. The theme of this year's event is 'True Partnership Amidst Changing Times', reinforcing ASE's commitment to position itself strategically as a long term partner of its customers. The 2-day event in Hsinchu, Taiwan, will be followed by 5 other Tech Forums in major cities in Europe and Southeast Asia.

At the Hsinchu event, semiconductor professionals from the Taiwan silicon island are expected to gather to hear of the latest market trends, technology developments and solutions in the backend semiconductor packaging and test industry. ASE technology experts will deliver topics including ASE advanced technology developments and roadmaps, SoC (System on Chip) solutions, Total Flip Chip packaging and Wafer Bumping technology, SiP (System in Package) developments, Leadfree and Green Packages, System solutions for Wireless Communications and much more.

"The annual ASE Tech Forum serves as a platform for us to share views on the industry landscape and update our customers on the latest developments in ASE technology," said Tien Wu, President, ASE Group, Americas, Europe and Japan. "Markets evolve and our customers continue to face new challenges on the performance and cost parameters. Of a stronger focus this year, is our efforts to maximize next generation chip solutions and minimize the burden on our customers' resource allocation through effective manufacturing. Hence, our theme for 2003's Tech Forum centers around partnerships."

"This year, we chose Hsinchu, Taiwan to kick off the ASE Tech Forum 2003 series, emphasizing Taiwan's leadership in semiconductor manufacturing services. Hsinchu is the heartbeat of the Taiwan Cluster that provides services to worldwide customers," said K.J. Chin, President, ASE Group, Taiwan. "The cluster effect, together with our leading-edge technologies and optimized manufacturing services allow us to help the customer enhance IC performance and speed up time-to-market,"

"The annual ASE Tech Forum has been a significant technology trend indicator for the

semiconductor backend manufacturing industry. Through dynamic interactions with the participants, we expect to set future roadmaps and blueprints for the industry's overall technology development efforts," said J.J. Lee, President, Research and Development, ASE Group.

ASE Tech Forum 2003 will also be held in Herzliya, Israel (Oct 2), Grenoble, France (Oct 7), Munich, Germany (Oct 10), Penang, Malaysia (Nov 5) and Singapore (Nov 7). For more information, please visit <http://www.asetechforum.com>.

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